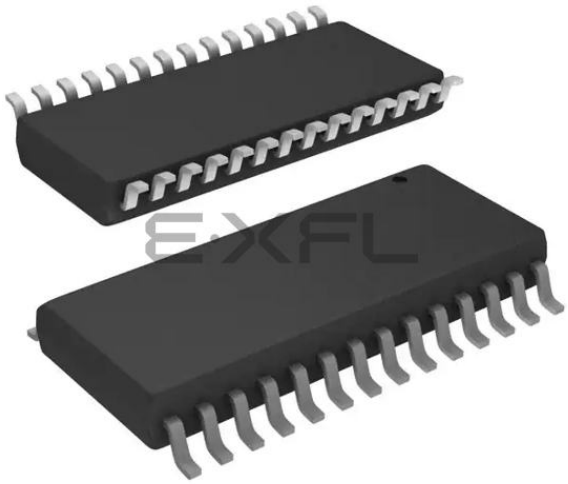

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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	40MHz
Connectivity	I²C, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, LVD, POR, PWM, WDT
Number of I/O	22
Program Memory Size	16KB (8K x 16)
Program Memory Type	OTP
EEPROM Size	-
RAM Size	512 x 8
Voltage - Supply (Vcc/Vdd)	4.2V ~ 5.5V
Data Converters	A/D 5x10b
Oscillator Type	External
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	28-SOIC (0.295", 7.50mm Width)
Supplier Device Package	28-SOIC
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic18c242-i-so

TABLE 2-2: CAPACITOR SELECTION FOR CRYSTAL OSCILLATORS

Ranges Tested:			
Mode	**Freq**	**C1**	**C2**
LP	32.0 kHz	33 pF	33 pF
	200 kHz	15 pF	15 pF
XT	200 kHz	47-68 pF	47-68 pF
	1.0 MHz	15 pF	15 pF
	4.0 MHz	15 pF	15 pF
HS	4.0 MHz	15 pF	15 pF
	8.0 MHz	15-33 pF	15-33 pF
	20.0 MHz	15-33 pF	15-33 pF
	25.0 MHz	15-33 pF	15-33 pF
These values are for design guidance only. See notes following this table.			
Crystals Used			
32.0 kHz	Epson C-001R32.768K-A	± 20 PPM	
200 kHz	STD XTL 200.000kHz	± 20 PPM	
1.0 MHz	ECS ECS-10-13-1	± 50 PPM	
4.0 MHz	ECS ECS-40-20-1	± 50 PPM	
8.0 MHz	Epson CA-301 8.000M-C	± 30 PPM	
20.0 MHz	Epson CA-301 20.000M-C	± 30 PPM	

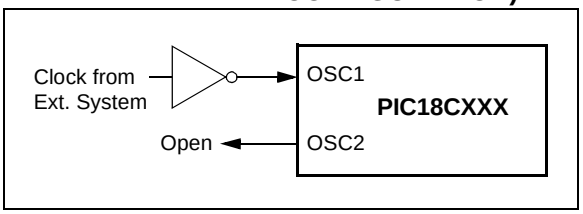
Note 1: Higher capacitance increases the stability of the oscillator, but also increases the start-up time.

2: Rs may be required in HS mode, as well as XT mode, to avoid overdriving crystals with low drive level specification.

3: Since each resonator/crystal has its own characteristics, the user should consult the resonator/crystal manufacturer for appropriate values of external components or verify oscillator performance.

An external clock source may also be connected to the OSC1 pin in these modes, as shown in Figure 2-2.

FIGURE 2-2: EXTERNAL CLOCK INPUT OPERATION (HS, XT OR LP CONFIGURATION)

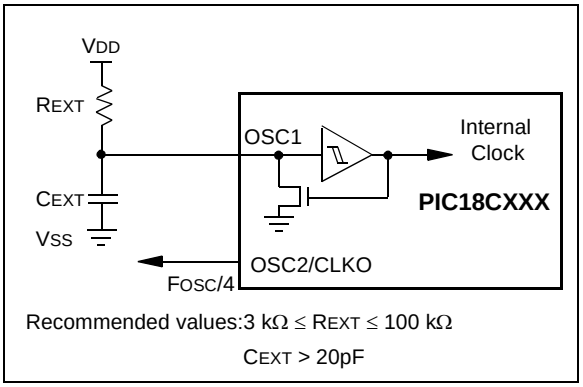


2.3 RC Oscillator

For timing insensitive applications, the “RC” and "RCIO" device options offer additional cost savings. The RC oscillator frequency is a function of the supply voltage, the resistor (REXT) and capacitor (CEXT) values and the operating temperature. In addition to this, the oscillator frequency will vary from unit to unit due to normal process parameter variation. Furthermore, the difference in lead frame capacitance between package types will also affect the oscillation frequency, especially for low CEXT values. The user also needs to take into account variation due to tolerance of external R and C components used. Figure 2-3 shows how the R/C combination is connected.

In the RC oscillator mode, the oscillator frequency divided by 4 is available on the OSC2 pin. This signal may be used for test purposes or to synchronize other logic.

FIGURE 2-3: RC OSCILLATOR MODE



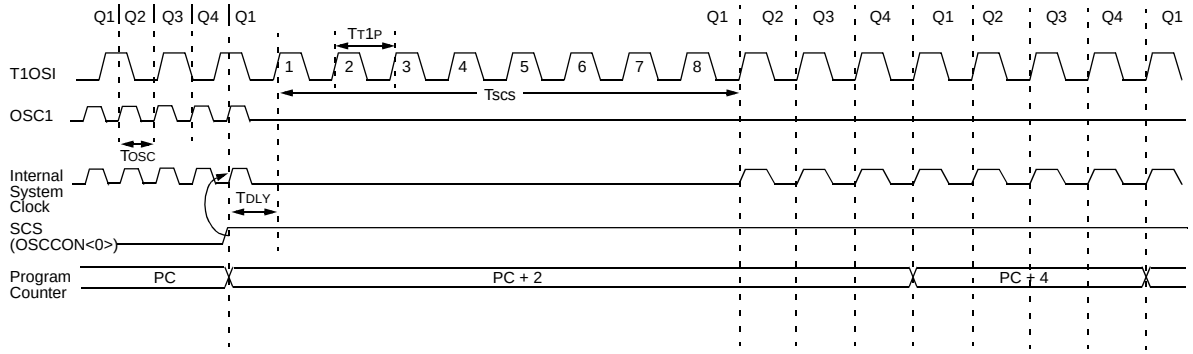
The RCIO oscillator mode functions like the RC mode, except that the OSC2 pin becomes an additional general purpose I/O pin. The I/O pin becomes bit 6 of PORTA (RA6).

2.6.2 OSCILLATOR TRANSITIONS

The PIC18CXX2 devices contain circuitry to prevent "glitches" when switching between oscillator sources. Essentially, the circuitry waits for eight rising edges of the clock source that the processor is switching to. This ensures that the new clock source is stable and that it's pulse width will not be less than the shortest pulse width of the two clock sources.

A timing diagram indicating the transition from the main oscillator to the Timer1 oscillator is shown in Figure 2-8. The Timer1 oscillator is assumed to be running all the time. After the SCS bit is set, the processor is frozen at the next occurring Q1 cycle. After eight synchronization cycles are counted from the Timer1 oscillator, operation resumes. No additional delays are required after the synchronization cycles.

FIGURE 2-8: TIMING DIAGRAM FOR TRANSITION FROM OSC1 TO TIMER1 OSCILLATOR

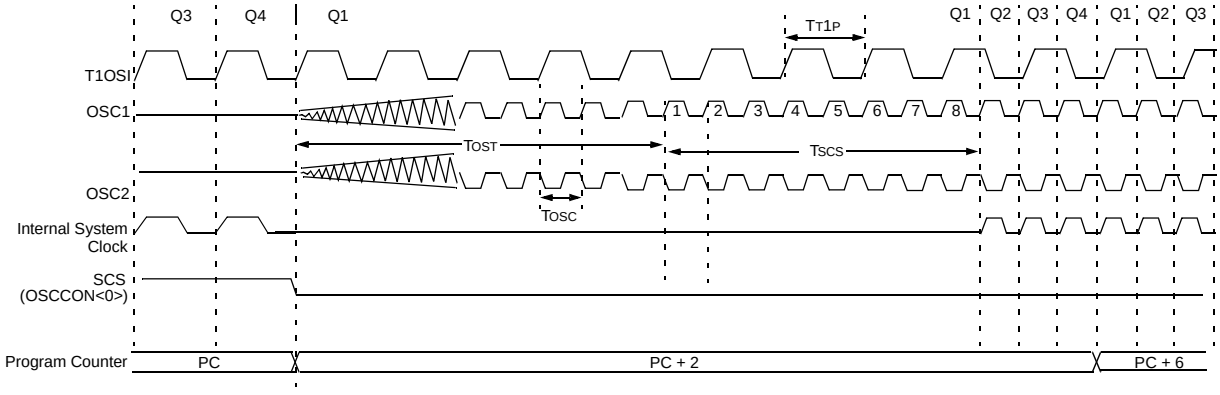


Note 1: Delay on internal system clock is eight oscillator cycles for synchronization.

The sequence of events that takes place when switching from the Timer1 oscillator to the main oscillator will depend on the mode of the main oscillator. In addition to eight clock cycles of the main oscillator, additional delays may take place.

If the main oscillator is configured for an external crystal (HS, XT, LP), then the transition will take place after an oscillator start-up time (TOST) has occurred. A timing diagram indicating the transition from the Timer1 oscillator to the main oscillator for HS, XT and LP modes is shown in Figure 2-9.

FIGURE 2-9: TIMING FOR TRANSITION BETWEEN TIMER1 AND OSC1 (HS, XT, LP)



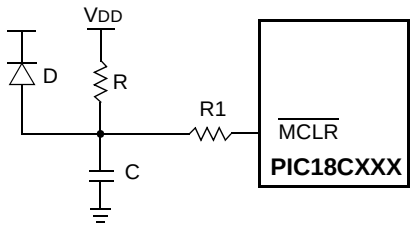
Note 1: TOST = 1024TOSC (drawing not to scale).

3.1 Power-on Reset (POR)

A Power-on Reset pulse is generated on-chip when VDD rise is detected. To take advantage of the POR circuitry, just tie the MCLR pin directly (or through a resistor) to VDD. This will eliminate external RC components usually needed to create a Power-on Reset delay. A minimum rise rate for VDD is specified (parameter D004). For a slow rise time, see Figure 3-2.

When the device starts normal operation (i.e., exits the RESET condition), device operating parameters (voltage, frequency, temperature, etc.) must be met to ensure operation. If these conditions are not met, the device must be held in reset until the operating conditions are met.

FIGURE 3-2: EXTERNAL POWER-ON RESET CIRCUIT (FOR SLOW VDD POWER-UP)



Note 1: External Power-on Reset circuit is required only if the VDD power-up slope is too slow. The diode D helps discharge the capacitor quickly when VDD powers down.

2: R < 40 kΩ is recommended to make sure that the voltage drop across R does not violate the device's electrical specification.

3: R1 = 100Ω to 1 kΩ will limit any current flowing into MCLR from external capacitor C in the event of MCLR/VPP pin breakdown, due to Electrostatic Discharge (ESD) or Electrical Overstress (EOS).

3.2 Power-up Timer (PWRT)

The Power-up Timer provides a fixed nominal time-out (parameter #33) only on power-up from the POR. The Power-up Timer operates on an internal RC oscillator. The chip is kept in reset as long as the PWRT is active. The PWRT's time delay allows VDD to rise to an acceptable level. A configuration bit is provided to enable/disable the PWRT.

The power-up time delay will vary from chip-to-chip due to VDD, temperature and process variation. See DC parameter #33 for details.

3.3 Oscillator Start-up Timer (OST)

The Oscillator Start-up Timer (OST) provides a 1024 oscillator cycle (from OSC1 input) delay after the PWRT delay is over (parameter #32). This ensures that the crystal oscillator or resonator has started and stabilized.

The OST time-out is invoked only for XT, LP and HS modes and only on Power-on Reset or wake-up from SLEEP.

3.4 PLL Lock Time-out

With the PLL enabled, the time-out sequence following a Power-on Reset is different from other oscillator modes. A portion of the Power-up Timer is used to provide a fixed time-out that is sufficient for the PLL to lock to the main oscillator frequency. This PLL lock time-out (TPLL) is typically 2 ms and follows the oscillator start-up time-out (OST).

3.5 Brown-out Reset (BOR)

A configuration bit, BOREN, can disable (if clear/programmed), or enable (if set) the Brown-out Reset circuitry. If VDD falls below parameter D005 for greater than parameter #35, the brown-out situation will reset the chip. A RESET may not occur if VDD falls below parameter D005 for less than parameter #35. The chip will remain in Brown-out Reset until VDD rises above BVDD. The Power-up Timer will then be invoked and will keep the chip in RESET an additional time delay (parameter #33). If VDD drops below BVDD while the Power-up Timer is running, the chip will go back into a Brown-out Reset and the Power-up Timer will be initialized. Once VDD rises above BVDD, the Power-up Timer will execute the additional time delay.

3.6 Time-out Sequence

On power-up, the time-out sequence is as follows: First, PWRT time-out is invoked after the POR time delay has expired. Then, OST is activated. The total time-out will vary based on oscillator configuration and the status of the PWRT. For example, in RC mode with the PWRT disabled, there will be no time-out at all. Figure 3-3, Figure 3-4, Figure 3-5, Figure 3-6 and Figure 3-7 depict time-out sequences on power-up.

Since the time-outs occur from the POR pulse, if MCLR is kept low long enough, the time-outs will expire. Bringing MCLR high will begin execution immediately (Figure 3-5). This is useful for testing purposes or to synchronize more than one PIC18CXXX device operating in parallel.

Table 3-2 shows the RESET conditions for some Special Function Registers, while Table 3-3 shows the RESET conditions for all the registers.

NOTES:

TABLE 4-2: REGISTER FILE SUMMARY

File Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR, BOR	Details on page:
TOSU	—	—	—	Top-of-Stack Upper Byte (TOS<20:16>)					---0 0000	37
TOSH	Top-of-Stack High Byte (TOS<15:8>)								0000 0000	37
TOSL	Top-of-Stack Low Byte (TOS<7:0>)								0000 0000	37
STKPTR	STKFUL	STKUNF	—	Return Stack Pointer					00-0 0000	38
PCLATU	—	—	—	Holding Register for PC<20:16>					---0 0000	39
PCLATH	Holding Register for PC<15:8>								0000 0000	39
PCL	PC Low Byte (PC<7:0>)								0000 0000	39
TBLPTRU	—	—	bit21(2)	Program Memory Table Pointer Upper Byte (TBLPTR<20:16>)					---0 0000	57
TBLPTRH	Program Memory Table Pointer High Byte (TBLPTR<15:8>)								0000 0000	57
TBLPTRL	Program Memory Table Pointer Low Byte (TBLPTR<7:0>)								0000 0000	57
TABLAT	Program Memory Table Latch								0000 0000	57
PRODH	Product Register High Byte								xxxx xxxx	61
PRODL	Product Register Low Byte								xxxx xxxx	61
INTCON	GIE/GIEH	PEIE/GIEL	TMR0IE	INT0IE	RBIE	TMR0IF	INT0IF	RBIF	0000 000x	65
INTCON2	RBPU	INTEDG0	INTEDG1	INTEDG2	—	TMR0IP	—	RBIP	1111 -1-1	66
INTCON3	INT2IP	INT1IP	—	INT2IE	INT1IE	—	INT2IF	INT1IF	11-0 0-00	67
INDF0	Uses contents of FSR0 to address data memory - value of FSR0 not changed (not a physical register)								N/A	50
POSTINC0	Uses contents of FSR0 to address data memory - value of FSR0 post-incremented (not a physical register)								N/A	50
POSTDEC0	Uses contents of FSR0 to address data memory - value of FSR0 post-decremented (not a physical register)								N/A	50
PREINC0	Uses contents of FSR0 to address data memory - value of FSR0 pre-incremented (not a physical register)								N/A	50
PLUSW0	Uses contents of FSR0 to address data memory - value of FSR0 pre-incremented (not a physical register) - value of FSR0 offset by value in WREG								N/A	50
FSR0H	—	—	—	—	Indirect Data Memory Address Pointer 0 High Byte				---- 0000	50
FSR0L	Indirect Data Memory Address Pointer 0 Low Byte								xxxx xxxx	50
WREG	Working Register								xxxx xxxx	
INDF1	Uses contents of FSR1 to address data memory - value of FSR1 not changed (not a physical register)								N/A	50
POSTINC1	Uses contents of FSR1 to address data memory - value of FSR1 post-incremented (not a physical register)								N/A	50
POSTDEC1	Uses contents of FSR1 to address data memory - value of FSR1 post-decremented (not a physical register)								N/A	50
PREINC1	Uses contents of FSR1 to address data memory - value of FSR1 pre-incremented (not a physical register)								N/A	50
PLUSW1	Uses contents of FSR1 to address data memory - value of FSR1 pre-incremented (not a physical register) - value of FSR1 offset by value in WREG								N/A	50
FSR1H	—	—	—	—	Indirect Data Memory Address Pointer 1 High Byte				---- 0000	50
FSR1L	Indirect Data Memory Address Pointer 1 Low Byte								xxxx xxxx	50
BSR	—	—	—	—	Bank Select Register				---- 0000	49
INDF2	Uses contents of FSR2 to address data memory - value of FSR2 not changed (not a physical register)								N/A	50
POSTINC2	Uses contents of FSR2 to address data memory - value of FSR2 post-incremented (not a physical register)								N/A	50
POSTDEC2	Uses contents of FSR2 to address data memory - value of FSR2 post-decremented (not a physical register)								N/A	50
PREINC2	Uses contents of FSR2 to address data memory - value of FSR2 pre-incremented (not a physical register)								N/A	50
PLUSW2	Uses contents of FSR2 to address data memory - value of FSR2 pre-incremented (not a physical register) - value of FSR2 offset by value in WREG								N/A	50
FSR2H	—	—	—	—	Indirect Data Memory Address Pointer 2 High Byte				---- 0000	50
FSR2L	Indirect Data Memory Address Pointer 2 Low Byte								xxxx xxxx	50
STATUS	—	—	—	N	OV	Z	DC	C	---x xxxx	52
TMR0H	Timer0 Register High Byte								0000 0000	95
TMR0L	Timer0 Register Low Byte								xxxx xxxx	95
T0CON	TMR0ON	T08BIT	T0CS	T0SE	PSA	T0PS2	T0PS1	T0PS0	1111 1111	93
OSCCON	—	—	—	—	—	—	—	SCS	---- ---0	20
LVDCON	—	—	IRVST	LVDEN	LVDL3	LVDL2	LVDL1	LVDL0	--00 0101	175

Legend: x = unknown, u = unchanged, - = unimplemented, q = value depends on condition

Note 1: RA6 and associated bits are configured as port pins in RCIO and ECIO oscillator mode only, and read '0' in all other oscillator modes.

2: Bit 21 of the TBLPTRU allows access to the device configuration bits.

4.10 Access Bank

The Access Bank is an architectural enhancement, which is very useful for C compiler code optimization. The techniques used by the C compiler may also be useful for programs written in assembly.

This data memory region can be used for:

- Intermediate computational values
- Local variables of subroutines
- Faster context saving/switching of variables
- Common variables
- Faster evaluation/control of SFRs (no banking)

The Access Bank is comprised of the upper 128 bytes in Bank 15 (SFRs) and the lower 128 bytes in Bank 0. These two sections will be referred to as Access RAM High and Access RAM Low, respectively. Figure 4-6 and Figure 4-7 indicate the Access RAM areas.

A bit in the instruction word specifies if the operation is to occur in the bank specified by the BSR register or in the Access Bank. This bit is denoted by the 'a' bit (for access bit).

When forced in the Access Bank (a = '0'), the last address in Access RAM Low is followed by the first address in Access RAM High. Access RAM High maps the Special Function registers, so that these registers can be accessed without any software overhead. This is useful for testing status flags and modifying control bits.

4.11 Bank Select Register (BSR)

The need for a large general purpose memory space dictates a RAM banking scheme. The data memory is partitioned into sixteen banks. When using direct addressing, the BSR should be configured for the desired bank.

BSR<3:0> holds the upper 4 bits of the 12-bit RAM address. The BSR<7:4> bits will always read '0's, and writes will have no effect.

A `MOVLB` instruction has been provided in the instruction set to assist in selecting banks.

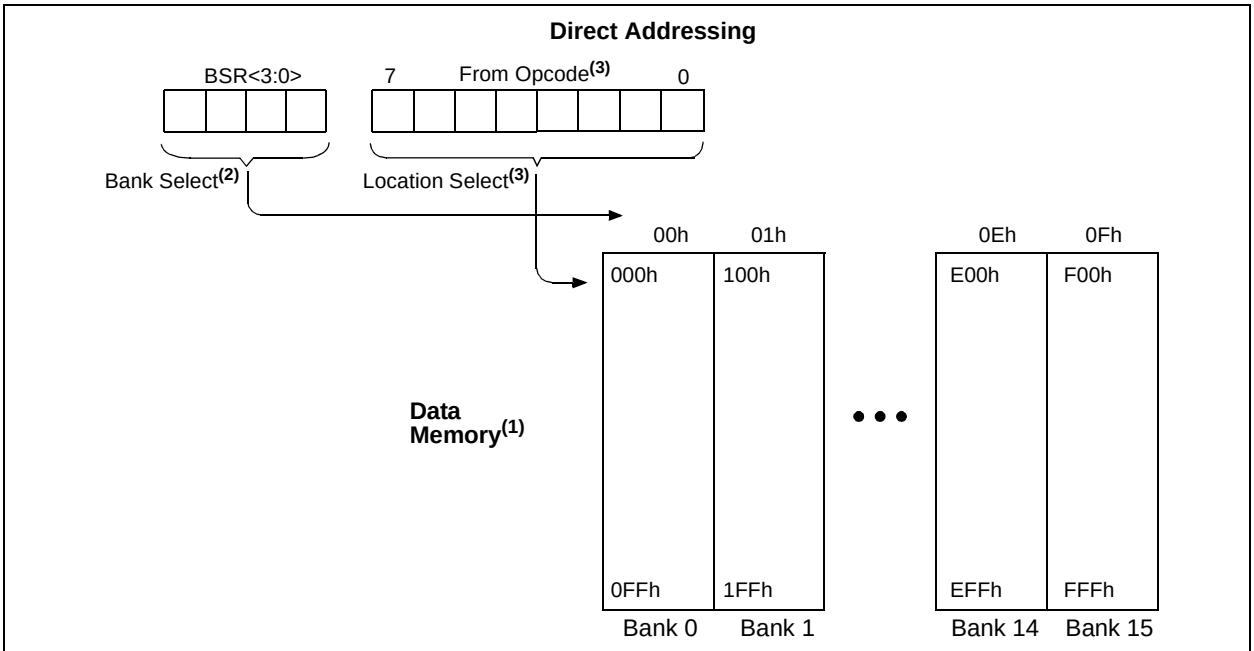
If the currently selected bank is not implemented, any read will return all '0's and all writes are ignored. The STATUS register bits will be set/cleared as appropriate for the instruction performed.

Each Bank extends up to FFh (256 bytes). All data memory is implemented as static RAM.

A `MOVFF` instruction ignores the BSR, since the 12-bit addresses are embedded into the instruction word.

Section 4.12 provides a description of indirect addressing, which allows linear addressing of the entire RAM space.

FIGURE 4-8: DIRECT ADDRESSING



Note 1: For register file map detail, see Table 4-1.

2: The access bit of the instruction can be used to force an override of the selected bank (BSR<3:0>) to the registers of the Access Bank.

3: The `MOVFF` instruction embeds the entire 12-bit address in the instruction.

NOTES:

8.2 PORTB, TRISB and LATB Registers

PORTB is an 8-bit wide, bi-directional port. The corresponding data direction register is TRISB. Setting a TRISB bit (= 1) will make the corresponding PORTB pin an input (i.e., put the corresponding output driver in a Hi-Impedance mode). Clearing a TRISB bit (= 0) will make the corresponding PORTB pin an output (i.e., put the contents of the output latch on the selected pin).

Note:	On a Power-on Reset, these pins are configured as digital inputs.

The Data Latch register (LATB) is also memory mapped. Read-modify-write operations on the LATB register reads and writes the latched output value for PORTB.

EXAMPLE 8-2: INITIALIZING PORTB

```
CLRF    PORTB    ; Initialize PORTB by
                 ; clearing output
                 ; data latches
CLRF    LATB     ; Alternate method
                 ; to clear output
                 ; data latches
MOVLW 0xCF       ; Value used to
                 ; initialize data
                 ; direction
MOVWF TRISB      ; Set RB<3:0> as inputs
                 ; RB<5:4> as outputs
                 ; RB<7:6> as inputs
```

Each of the PORTB pins has a weak internal pull-up. A single control bit can turn on all the pull-ups. This is performed by clearing bit $\overline{\text{RBPU}}$ (INTCON2<7>). The weak pull-up is automatically turned off when the port pin is configured as an output. The pull-ups are disabled on a Power-on Reset.

Four of the PORTB pins, RB7:RB4, have an interrupt-on-change feature. Only pins configured as inputs can cause this interrupt to occur (i.e., any RB7:RB4 pin configured as an output is excluded from the interrupt-on-change comparison). The input pins (of RB7:RB4) are compared with the old value latched on the last read of PORTB. The “mismatch” outputs of RB7:RB4 are OR’ed together to generate the RB Port Change Interrupt with flag bit RBIF (INTCON<0>).

This interrupt can wake the device from SLEEP. The user, in the Interrupt Service Routine, can clear the interrupt in the following manner:

a) Any read or write of PORTB (except with the MOVFF instruction). This will end the mismatch condition.

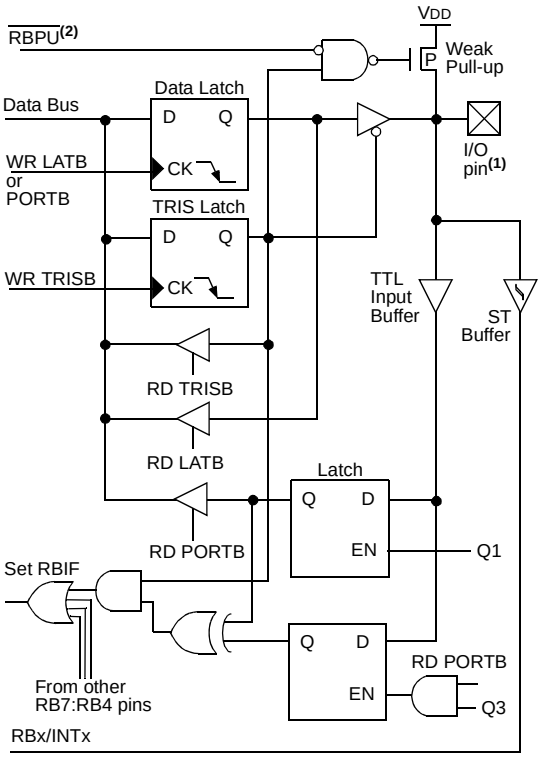
b) Clear flag bit RBIF.

A mismatch condition will continue to set flag bit RBIF. Reading PORTB will end the mismatch condition and allow flag bit RBIF to be cleared.

The interrupt-on-change feature is recommended for wake-up on key depression operation and operations where PORTB is only used for the interrupt-on-change feature. Polling of PORTB is not recommended while using the interrupt-on-change feature.

RB3 can be configured by the configuration bit CCP2MX as the alternate peripheral pin for the CCP2 module (CCP2MX = ‘0’).

FIGURE 8-4: BLOCK DIAGRAM OF RB7:RB4 PINS



Note 1: I/O pins have diode protection to VDD and VSS.

2: To enable weak pull-ups, set the appropriate TRIS bit(s) and clear the $\overline{\text{RBPU}}$ bit (INTCON2<7>).

TABLE 8-5: PORTC FUNCTIONS

Name	Bit#	Buffer Type	Function
RC0/T1OSO/T1CKI	bit0	ST	Input/output port pin or Timer1 oscillator output/Timer1 clock input.
RC1/T1OSI/CCP2	bit1	ST	Input/output port pin, Timer1 oscillator input, or Capture2 input/ Compare2 output/PWM output when CCP2MX configuration bit is disabled.
RC2/CCP1	bit2	ST	Input/output port pin or Capture1 input/Compare1 output/ PWM1 output.
RC3/SCK/SCL	bit3	ST	RC3 can also be the synchronous serial clock for both SPI and I^2C modes.
RC4/SDI/SDA	bit4	ST	RC4 can also be the SPI Data In (SPI mode) or Data I/O (I^2C mode).
RC5/SDO	bit5	ST	Input/output port pin or Synchronous Serial Port Data output.
RC6/TX/CK	bit6	ST	Input/output port pin, Addressable USART Asynchronous Transmit, or Addressable USART Synchronous Clock.
RC7/RX/DT	bit7	ST	Input/output port pin, Addressable USART Asynchronous Receive, or Addressable USART Synchronous Data.

Legend: ST = Schmitt Trigger input

TABLE 8-6: SUMMARY OF REGISTERS ASSOCIATED WITH PORTC

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR, BOR	Value on all other RESETS
PORTC	RC7	RC6	RC5	RC4	RC3	RC2	RC1	RC0	xxxx xxxx	uuuu uuuu
LATC	LATC Data Output Register								xxxx xxxx	uuuu uuuu
TRISC	PORTC Data Direction Register								1111 1111	1111 1111

Legend: x = unknown, u = unchanged

10.1 Timer1 Operation

Timer1 can operate in one of these modes:

- As a timer
- As a synchronous counter
- As an asynchronous counter

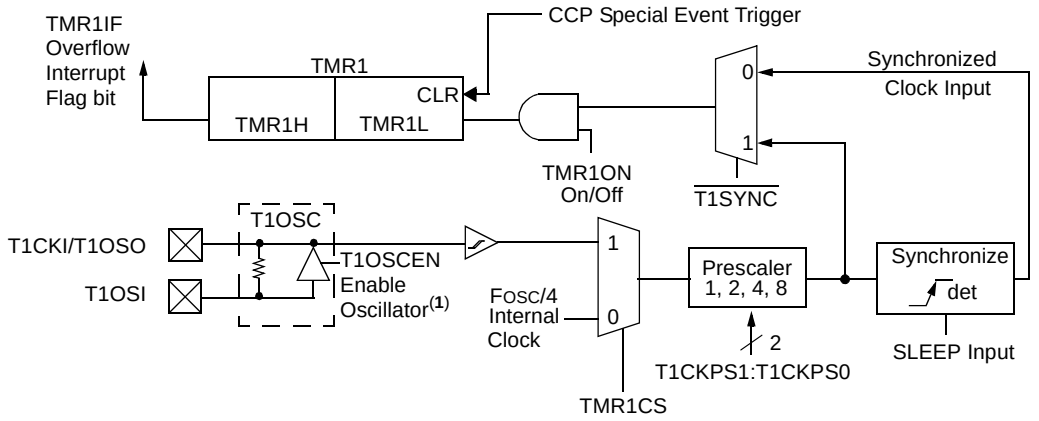
The operating mode is determined by the clock select bit, TMR1CS (T1CON<1>).

When TMR1CS = 0, Timer1 increments every instruction cycle. When TMR1CS = 1, Timer1 increments on every rising edge of the external clock input or the Timer1 oscillator, if enabled.

When the Timer1 oscillator is enabled (T1OSCEN is set), the RC1/T1OSI and RC0/T1OSO/T1CKI pins become inputs. That is, the TRISC<1:0> value is ignored.

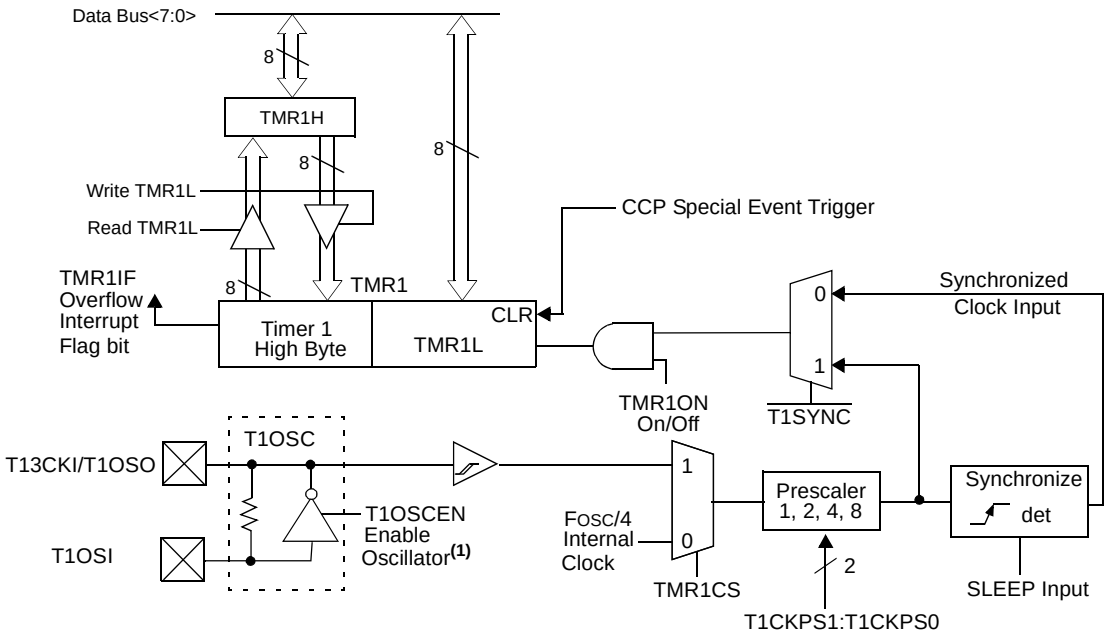
Timer1 also has an internal “RESET input”. This RESET can be generated by the CCP module (Section 13.0).

FIGURE 10-1: TIMER1 BLOCK DIAGRAM



Note 1: When enable bit T1OSCEN is cleared, the inverter and feedback resistor are turned off. This eliminates power drain.

FIGURE 10-2: TIMER1 BLOCK DIAGRAM: 16-BIT READ/WRITE MODE



Note 1: When enable bit T1OSCEN is cleared, the inverter and feedback resistor are turned off. This eliminates power drain.

12.0 TIMER3 MODULE

The Timer3 module timer/counter has the following features:

- 16-bit timer/counter
  (two 8-bit registers: TMR3H and TMR3L)
- Readable and writable (both registers)
- Internal or external clock select
- Interrupt-on-overflow from FFFFh to 0000h
- Reset from CCP module trigger

Figure 12-1 is a simplified block diagram of the Timer3 module.

Register 12-1 shows the Timer3 control register. This register controls the operating mode of the Timer3 module and sets the CCP clock source.

Register 10-1 shows the Timer1 control register. This register controls the operating mode of the Timer1 module, as well as contains the Timer1 oscillator enable bit (T1OSCEN), which can be a clock source for Timer3.

REGISTER 12-1: T3CON: TIMER3 CONTROL REGISTER

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
RD16	T3CCP2	T3CKPS1	T3CKPS0	T3CCP1	$\overline{\text{T3SYNC}}$	TMR3CS	TMR3ON
bit 7							bit 0

bit 7 **RD16:** 16-bit Read/Write Mode Enable
1 = Enables register Read/Write of Timer3 in one 16-bit operation
0 = Enables register Read/Write of Timer3 in two 8-bit operations

bit 6-3 **T3CCP2:T3CCP1:** Timer3 and Timer1 to CCPx Enable bits
1x = Timer3 is the clock source for compare/capture CCP modules
01 = Timer3 is the clock source for compare/capture of CCP2,
Timer1 is the clock source for compare/capture of CCP1
00 = Timer1 is the clock source for compare/capture CCP modules

bit 5-4 **T3CKPS1:T3CKPS0**: Timer3 Input Clock Prescale Select bits
11 = 1:8 Prescale value
10 = 1:4 Prescale value
01 = 1:2 Prescale value
00 = 1:1 Prescale value

bit 2 **$\overline{\text{T3SYNC}}$:** Timer3 External Clock Input Synchronization Control bit
(Not usable if the system clock comes from Timer1/Timer3.)
When TMR3CS = 1:
1 = Do not synchronize external clock input
0 = Synchronize external clock input
When TMR3CS = 0:
This bit is ignored. Timer3 uses the internal clock when TMR3CS = 0.

bit 1 **TMR3CS:** Timer3 Clock Source Select bit
1 = External clock input from Timer1 oscillator or T1CKI
(on the rising edge after the first falling edge)
0 = Internal clock (FOSC/4)

bit 0 **TMR3ON:** Timer3 On bit
1 = Enables Timer3
0 = Stops Timer3

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
- n = Value at POR reset	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

13.5.3 SETUP FOR PWM OPERATION

The following steps should be taken when configuring the CCP module for PWM operation:

1. Set the PWM period by writing to the PR2 register.
2. Set the PWM duty cycle by writing to the CCPR1L register and CCP1CON<5:4> bits.
3. Make the CCP1 pin an output by clearing the TRISC<2> bit.
4. Set the TMR2 prescale value and enable Timer2 by writing to T2CON.
5. Configure the CCP1 module for PWM operation.

TABLE 13-4: EXAMPLE PWM FREQUENCIES AND RESOLUTIONS AT 40 MHz

PWM Frequency	2.44 kHz	9.77 kHz	39.06 kHz	156.25 kHz	312.50 kHz	416.67 kHz
Timer Prescaler (1, 4, 16)	16	4	1	1	1	1
PR2 Value	0xFF	0xFF	0xFF	0x3F	0x1F	0x17
Maximum Resolution (bits)	14	12	10	8	7	6.58

TABLE 13-5: REGISTERS ASSOCIATED WITH PWM AND TIMER2

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR, BOR	Value on all other RESETS
INTCON	GIE/ GIEH	PEIE/ GIEL	TMR0IE	INT0IE	RBIE	TMR0IF	INT0IF	RBIF	0000 000x	0000 000u
PIR1	PSPIF(1)	ADIF	RCIF	TXIF	SSPIF	CCP1IF	TMR2IF	TMR1IF	0000 0000	0000 0000
PIE1	PSPIE(1)	ADIE	RCIE	TXIE	SSPIE	CCP1IE	TMR2IE	TMR1IE	0000 0000	0000 0000
IPR1	PSPIP(1)	ADIP	RCIP	TXIP	SSPIP	CCP1IP	TMR2IP	TMR1IP	0000 0000	0000 0000
TRISC	PORTC Data Direction Register								1111 1111	1111 1111
TMR2	Timer2 Module Register								0000 0000	0000 0000
PR2	Timer2 Module Period Register								1111 1111	1111 1111
T2CON	—	TOUTPS3	TOUTPS2	TOUTPS1	TOUTPS0	TMR2ON	T2CKPS1	T2CKPS0	-000 0000	-000 0000
CCPR1L	Capture/Compare/PWM Register1 (LSB)								xxxx xxxx	uuuu uuuu
CCPR1H	Capture/Compare/PWM Register1 (MSB)								xxxx xxxx	uuuu uuuu
CCP1CON	—	—	DC1B1	DC1B0	CCP1M3	CCP1M2	CCP1M1	CCP1M0	--00 0000	--00 0000
CCPR2L	Capture/Compare/PWM Register2 (LSB)								xxxx xxxx	uuuu uuuu
CCPR2H	Capture/Compare/PWM Register2 (MSB)								xxxx xxxx	uuuu uuuu
CCP2CON	—	—	DC2B1	DC2B0	CCP2M3	CCP2M2	CCP2M1	CCP2M0	--00 0000	--00 0000

Legend: x = unknown, u = unchanged, - = unimplemented, read as '0'. Shaded cells are not used by PWM and Timer2.

Note 1: The PSPIF, PSPIE and PSPIP bits are reserved on the PIC18C2X2 devices. Always maintain these bits clear.

14.4.2 GENERAL CALL ADDRESS SUPPORT

The addressing procedure for the I^2C bus is such that the first byte after the START condition usually determines which device will be the slave addressed by the master. The exception is the general call address which can address all devices. When this address is used, all devices should, in theory, respond with an acknowledge.

The general call address is one of eight addresses reserved for specific purposes by the I^2C protocol. It consists of all 0's with R/$\overline{W}$ = 0.

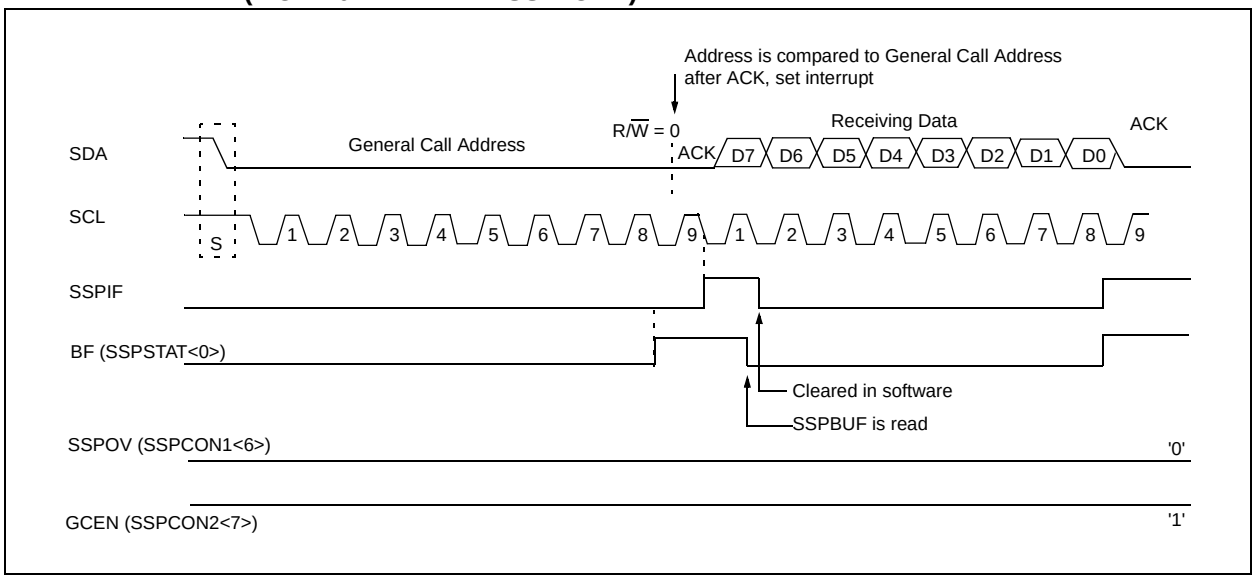
The general call address is recognized when the General Call Enable bit (GCEN) is enabled (SSPCON2<7> is set). Following a START bit detect, 8-bits are shifted into the SSPSR and the address is compared against the SSPADD. It is also compared to the general call address and fixed in hardware.

If the general call address matches, the SSPSR is transferred to the SSPBUF, the BF flag bit is set (eighth bit), and on the falling edge of the ninth bit ($\overline{ACK}$ bit), the SSPIF interrupt flag bit is set.

When the interrupt is serviced, the source for the interrupt can be checked by reading the contents of the SSPBUF. The value can be used to determine if the address was device specific or a general call address.

In 10-bit mode, the SSPADD is required to be updated for the second half of the address to match, and the UA bit is set (SSPSTAT<1>). If the general call address is sampled when the GCEN bit is set, while the slave is configured in 10-bit address mode, then the second half of the address is not necessary, the UA bit will not be set, and the slave will begin receiving data after the Acknowledge (Figure 14-12).

FIGURE 14-12: SLAVE MODE GENERAL CALL ADDRESS SEQUENCE (7 OR 10-BIT ADDRESS MODE)



14.4.3 MASTER MODE

Master mode of operation is supported by interrupt generation on the detection of the START and STOP conditions. The STOP (P) and START (S) bits are cleared from a RESET or when the MSSP module is disabled. Control of the I^2C bus may be taken when the P bit is set, or the bus is idle, with both the S and P bits clear.

In Master mode, the SCL and SDA lines are manipulated by the MSSP hardware.

The following events will cause SSP Interrupt Flag bit, SSPIF, to be set (SSP interrupt, if enabled):

- START condition
- STOP condition
- Data transfer byte transmitted/received
- Acknowledge Transmit
- Repeated START

14.4.16.1 Bus Collision During a START Condition

During a START condition, a bus collision occurs if:

a) SDA or SCL are sampled low at the beginning of the START condition (Figure 14-24).

b) SCL is sampled low before SDA is asserted low (Figure 14-25).

During a START condition, both the SDA and the SCL pins are monitored.

If the SDA pin is already low, or the SCL pin is already low, then all of the following occur:

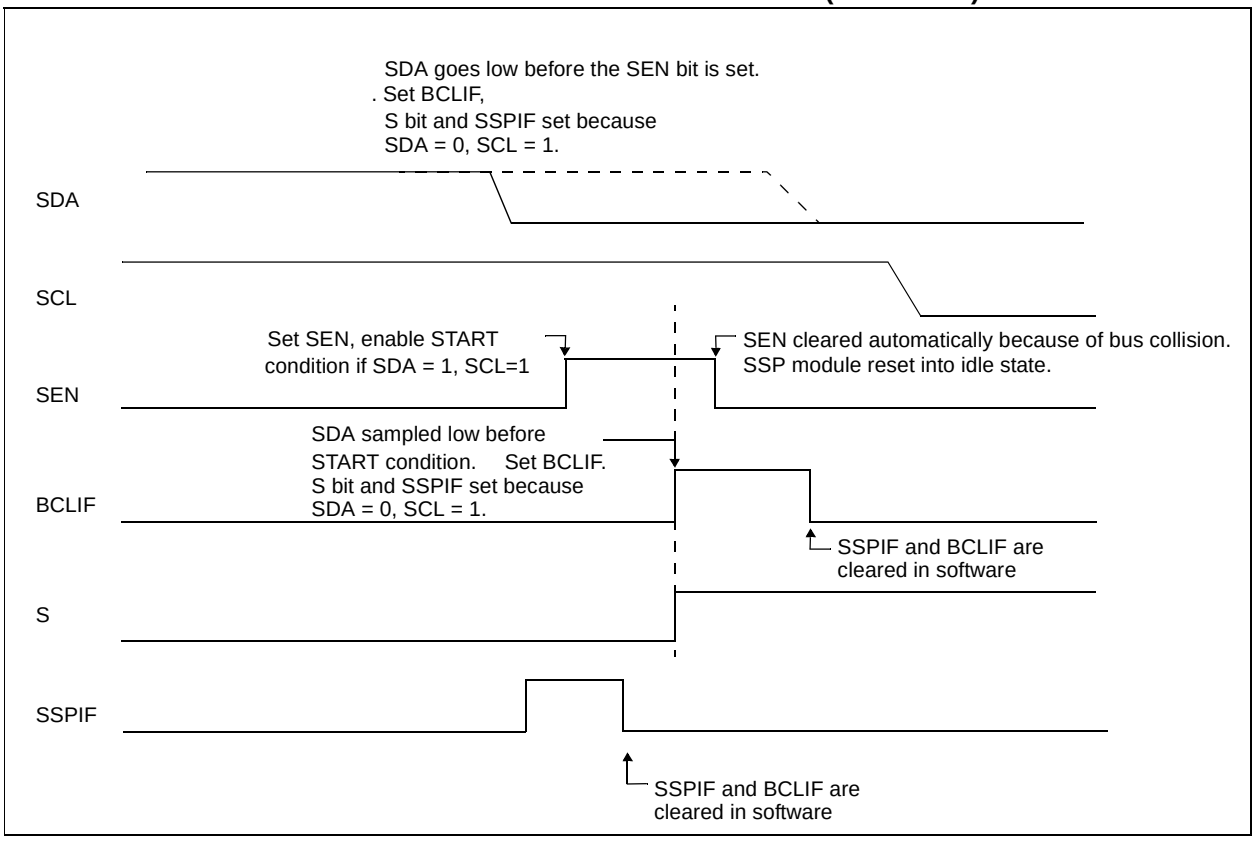
- the START condition is aborted,
- the BCLIF flag is set, and
- the MSSP module is reset to its IDLE state (Figure 14-24).

The START condition begins with the SDA and SCL pins de-asserted. When the SDA pin is sampled high, the baud rate generator is loaded from SSPADD<6:0> and counts down to 0. If the SCL pin is sampled low while SDA is high, a bus collision occurs, because it is assumed that another master is attempting to drive a data '1' during the START condition.

If the SDA pin is sampled low during this count, the BRG is reset and the SDA line is asserted early (Figure 14-26). If, however, a '1' is sampled on the SDA pin, the SDA pin is asserted low at the end of the BRG count. The baud rate generator is then reloaded and counts down to 0, and during this time, if the SCL pins are sampled as '0', a bus collision does not occur. At the end of the BRG count, the SCL pin is asserted low.

Note: The reason that bus collision is not a factor during a START condition, is that no two bus masters can assert a START condition at the exact same time. Therefore, one master will always assert SDA before the other. This condition does not cause a bus collision, because the two masters must be allowed to arbitrate the first address following the START condition. If the address is the same, arbitration must be allowed to continue into the data portion, Repeated START, or STOP conditions.

FIGURE 14-24: BUS COLLISION DURING START CONDITION (SDA ONLY)



14.4.16.3 Bus Collision During a STOP Condition

Bus collision occurs during a STOP condition if:

a) After the SDA pin has been de-asserted and allowed to float high, SDA is sampled low after the BRG has timed out.

b) After the SCL pin is de-asserted, SCL is sampled low before SDA goes high.

The STOP condition begins with SDA asserted low. When SDA is sampled low, the SCL pin is allowed to float. When the pin is sampled high (clock arbitration), the baud rate generator is loaded with SSPADD<6:0> and counts down to 0. After the BRG times out, SDA is sampled. If SDA is sampled low, a bus collision has occurred. This is due to another master attempting to drive a data '0' (Figure 14-29). If the SCL pin is sampled low before SDA is allowed to float high, a bus collision occurs. This is another case of another master attempting to drive a data '0' (Figure 14-30).

FIGURE 14-29: BUS COLLISION DURING A STOP CONDITION (CASE 1)

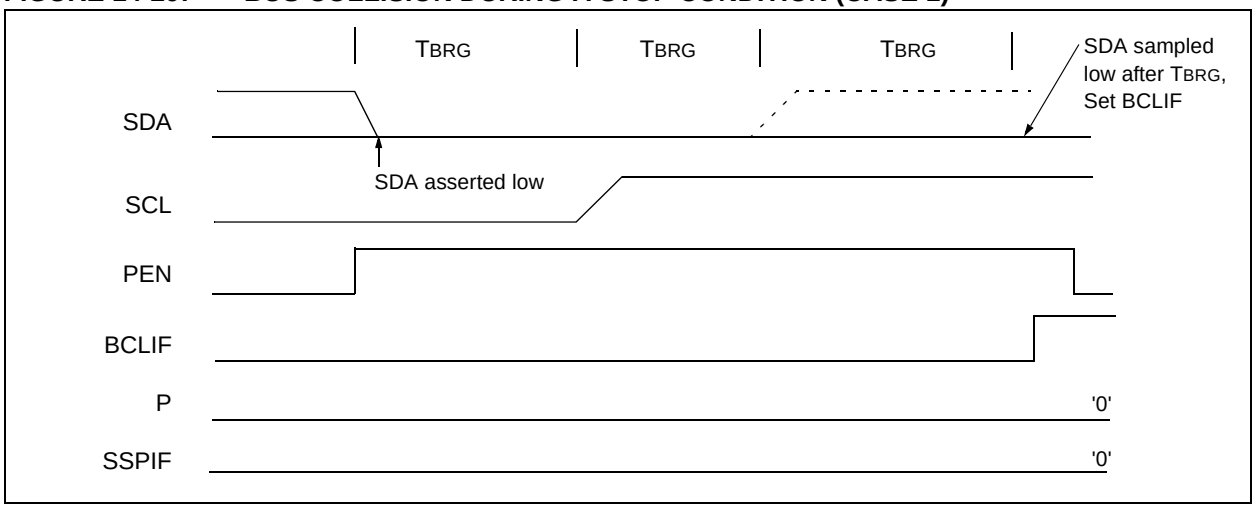


FIGURE 14-30: BUS COLLISION DURING A STOP CONDITION (CASE 2)

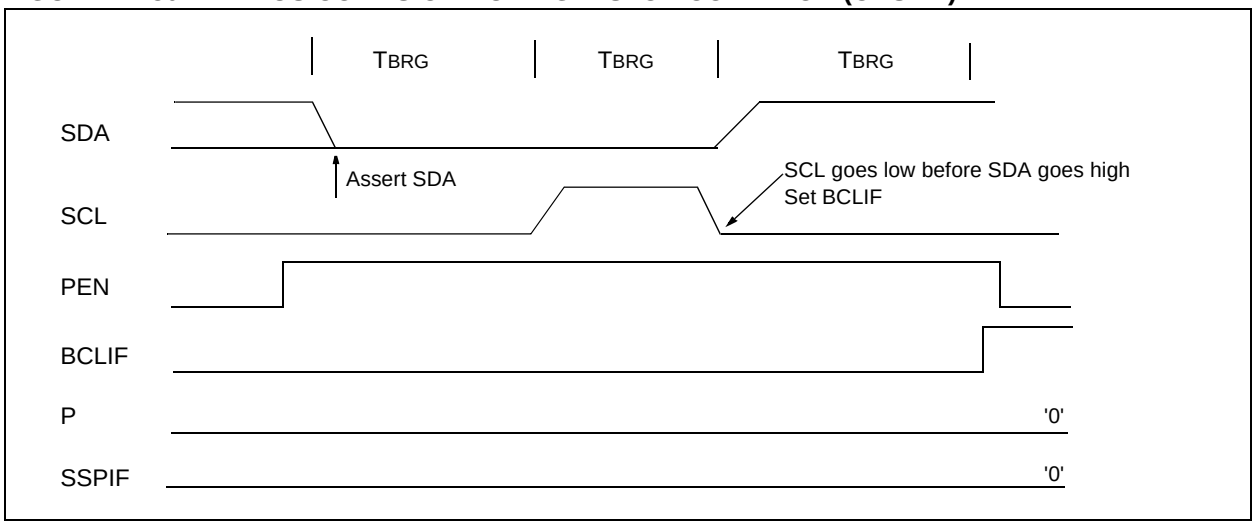


FIGURE 15-2: ASYNCHRONOUS TRANSMISSION

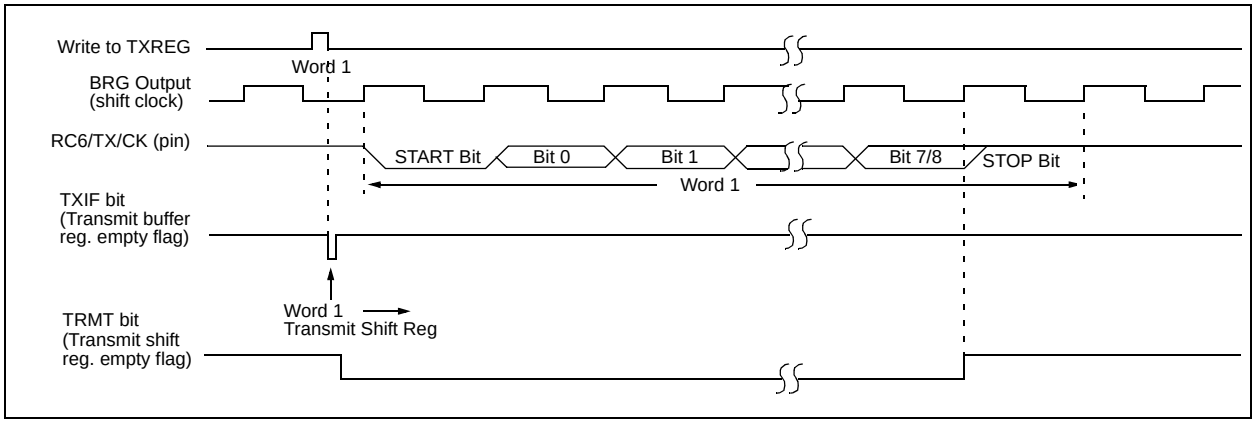
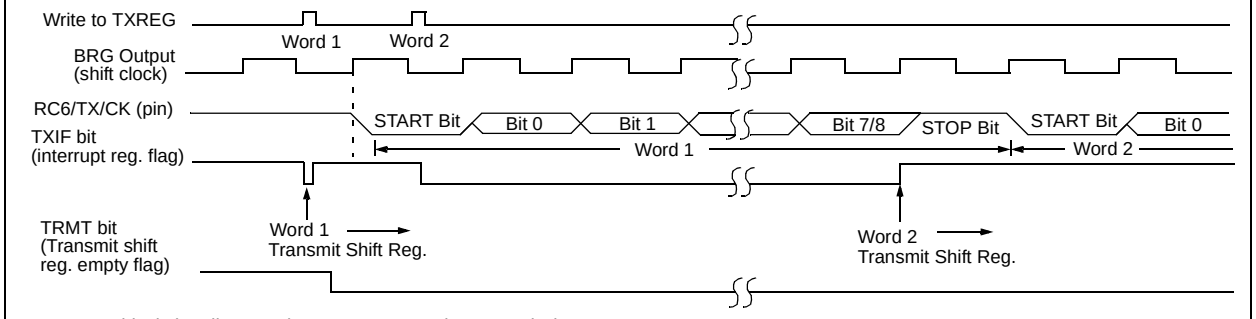


FIGURE 15-3: ASYNCHRONOUS TRANSMISSION (BACK TO BACK)



Note: This timing diagram shows two consecutive transmissions.

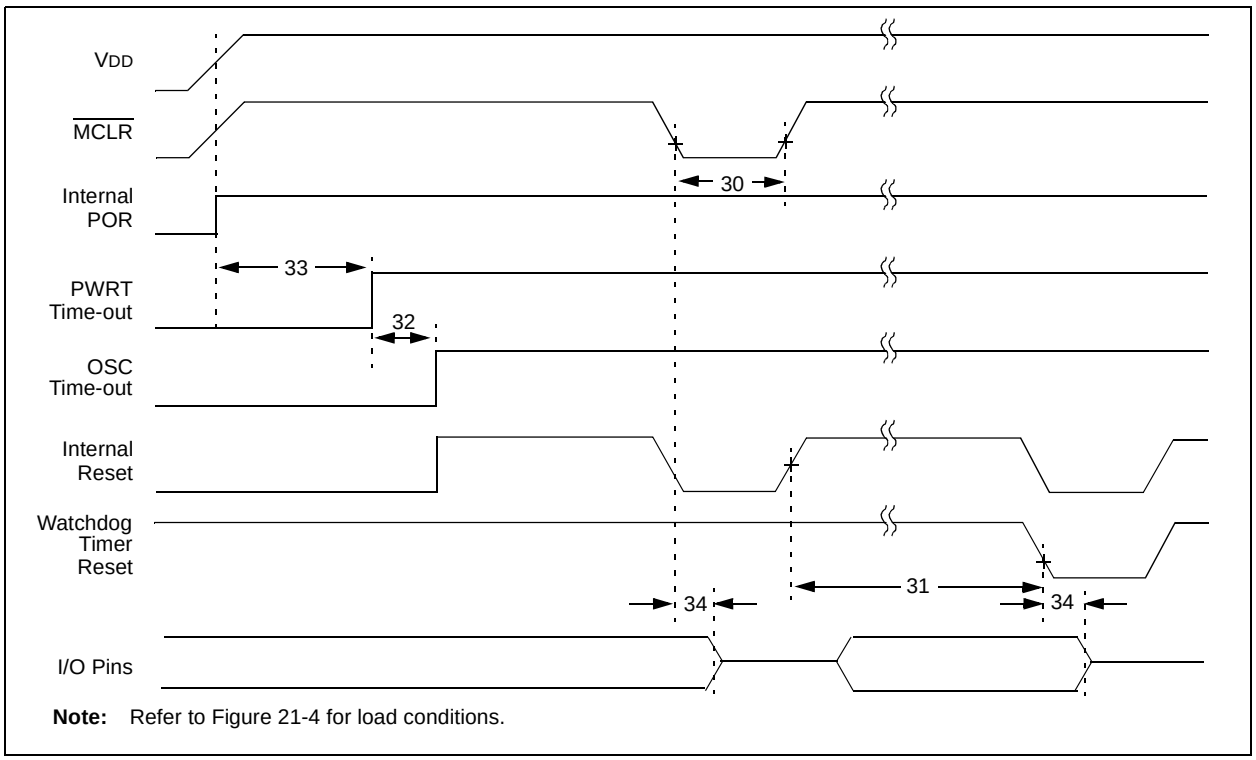
TABLE 15-6: REGISTERS ASSOCIATED WITH ASYNCHRONOUS TRANSMISSION

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR, BOR	Value on all other RESETS
INTCON	GIE/GIEH	PEIE/ GIEL	TMR0IE	INT0IE	RBIE	TMR0IF	INT0IF	RBIF	0000 000x	0000 000u
PIR1	PSPIF(1)	ADIF	RCIF	TXIF	SSPIF	CCP1IF	TMR2IF	TMR1IF	0000 0000	0000 0000
PIE1	PSPIE(1)	ADIE	RCIE	TXIE	SSPIE	CCP1IE	TMR2IE	TMR1IE	0000 0000	0000 0000
IPR1	PSPIP(1)	ADIP	RCIP	TXIP	SSPIP	CCP1IP	TMR2IP	TMR1IP	0000 0000	0000 0000
RCSTA	SPEN	RX9	SREN	CREN	ADDEN	FERR	OERR	RX9D	0000 -00x	0000 -00x
TXREG	USART Transmit Register								0000 0000	0000 0000
TXSTA	CSRC	TX9	TXEN	SYNC	—	BRGH	TRMT	TX9D	0000 -010	0000 -010
SPBRG	Baud Rate Generator Register								0000 0000	0000 0000

Legend: x = unknown, - = unimplemented locations read as '0'.
Shaded cells are not used for Asynchronous Transmission.

Note 1: The PSPIF, PSPIE and PSPIP bits are reserved on the PIC18C2X2 devices. Always maintain these bits clear.

FIGURE 21-7: RESET, WATCHDOG TIMER, OSCILLATOR START-UP TIMER AND POWER-UP TIMER TIMING



Note: Refer to Figure 21-4 for load conditions.

FIGURE 21-8: BROWN-OUT RESET TIMING

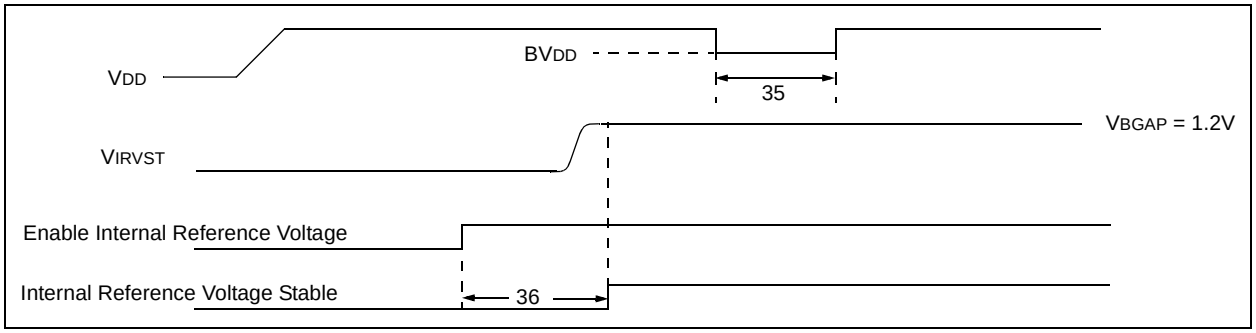
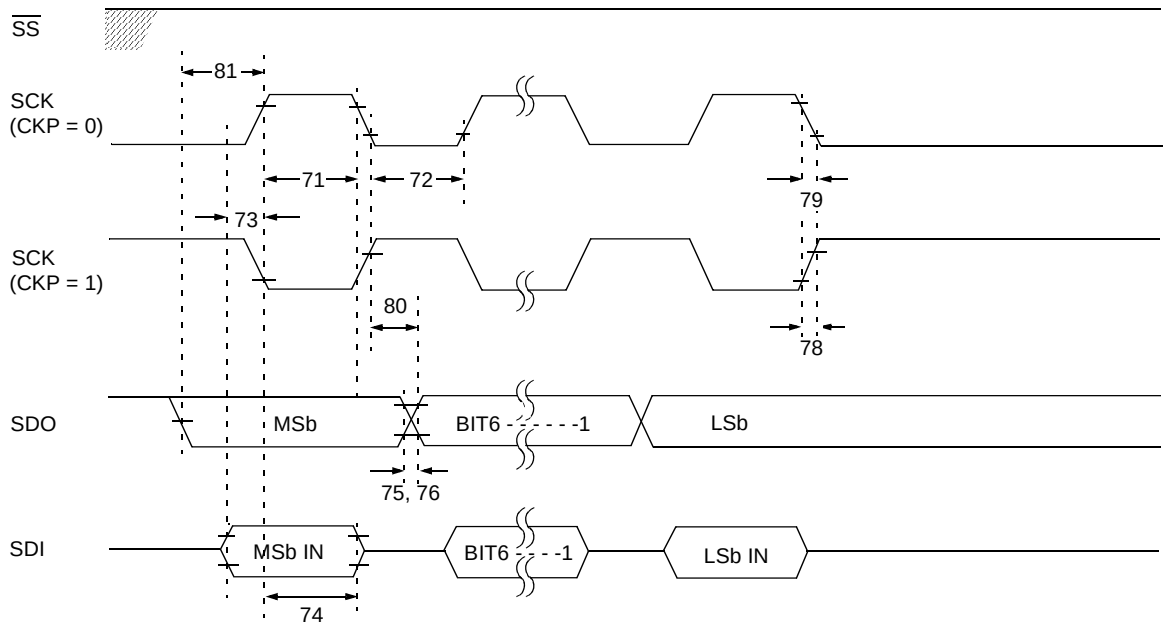


TABLE 21-7: RESET, WATCHDOG TIMER, OSCILLATOR START-UP TIMER, POWER-UP TIMER AND BROWN-OUT RESET REQUIREMENTS

Param. No.	Symbol	Characteristic	Min	Typ	Max	Units	Conditions
30	TmcL	$\overline{\text{MCLR}}$ Pulse Width (low)	2	—	—	µs	
31	TWDT	Watchdog Timer Time-out Period (No Postscaler)	7	18	33	ms	
32	TOST	Oscillation Start-up Timer Period	1024TOSC	—	1024TOSC	—	TOSC = OSC1 period
33	TPWRT	Power up Timer Period	28	72	132	ms	
34	TIOZ	I/O Hi-impedance from $\overline{\text{MCLR}}$ Low or Watchdog Timer Reset	—	2	—	µs	
35	TBOR	Brown-out Reset Pulse Width	200	—	—	µs	VDD ≤ BVDD (See D005)
36	Tivrst	Time for Internal Reference Voltage to become stable	—	20	50	µs	

FIGURE 21-13: EXAMPLE SPI MASTER MODE TIMING (CKE = 1)



Note: Refer to Figure 21-4 for load conditions.

TABLE 21-12: EXAMPLE SPI MODE REQUIREMENTS (MASTER MODE, CKE = 1)

Param. No.	Symbol	Characteristic		Min	Max	Units	Conditions
71	TscH	SCK input high time (Slave mode)	Continuous	1.25TCY + 30	—	ns	
71A			Single Byte	40	—	ns	**(Note 1)**
72	TscL	SCK input low time (Slave mode)	Continuous	1.25TCY + 30	—	ns	
72A			Single Byte	40	—	ns	**(Note 1)**
73	TdiV2scH, TdiV2scL	Setup time of SDI data input to SCK edge		100	—	ns	
73A	TB2B	Last clock edge of Byte1 to the 1st clock edge of Byte2		1.5TCY + 40	—	ns	**(Note 2)**
74	TscH2diL, TscL2diL	Hold time of SDI data input to SCK edge		100	—	ns	
75	TdoR	SDO data output rise time	PIC18**C**XXX	—	25	ns	
			PIC18**LC**XXX		45	ns	
76	TdoF	SDO data output fall time		—	25	ns	
78	TscR	SCK output rise time (Master mode)	PIC18**C**XXX	—	25	ns	
			PIC18**LC**XXX		45	ns	
79	TscF	SCK output fall time (Master mode)		—	25	ns	
80	TscH2doV, TscL2doV	SDO data output valid after SCK edge	PIC18**C**XXX	—	50	ns	
			PIC18**LC**XXX		100	ns	
81	TdoV2scH, TdoV2scL	SDO data output setup to SCK edge		TCY	—	ns	

Note 1: Requires the use of Parameter # 73A.
2: Only if Parameter # 71A and # 72A are used.

FIGURE 22-9: TYPICAL AND MAXIMUM IDD vs. VDD (TIMER1 AS MAIN OSCILLATOR, 32.768 kHz, C = 47 pF)

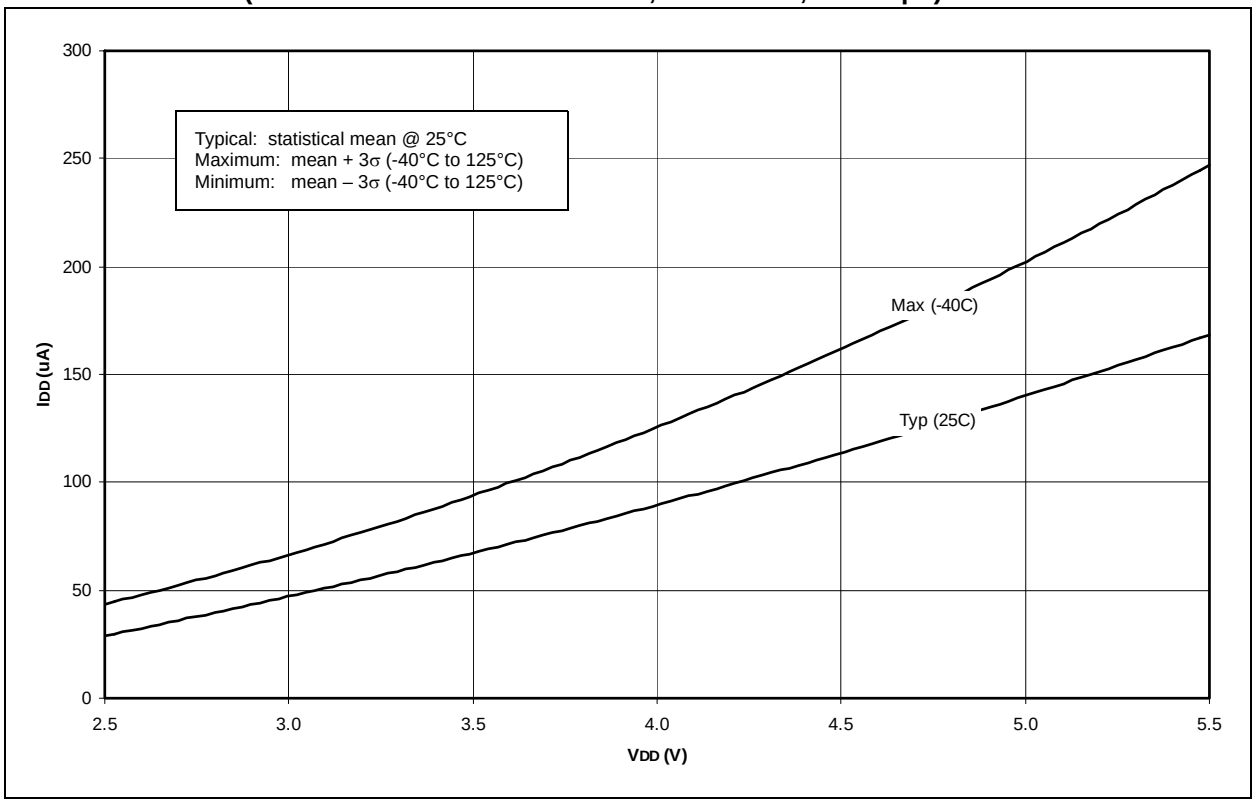


FIGURE 22-10: AVERAGE FOSC vs. VDD FOR VARIOUS VALUES OF R (RC MODE, C = 20 pF, 25°C)

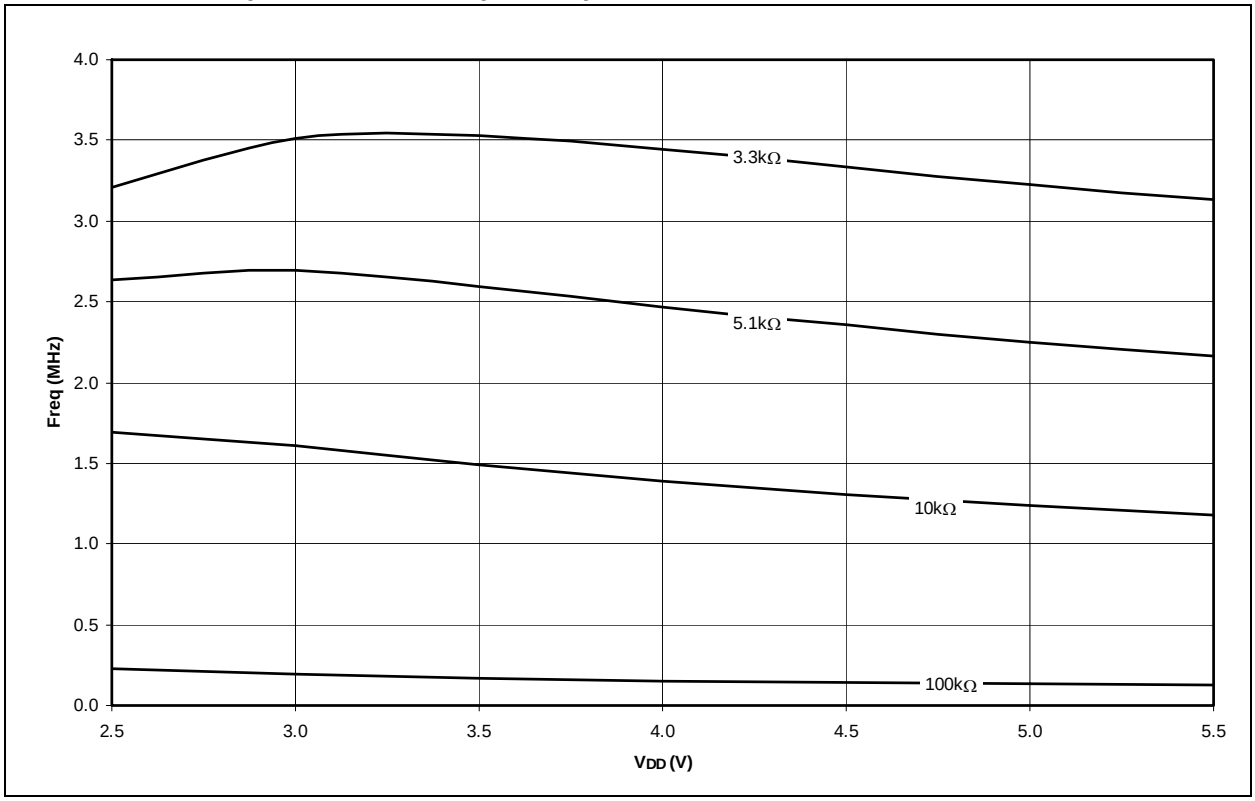


FIGURE 22-13: I_{PD} VS. V_{DD} (SLEEP MODE, ALL PERIPHERALS DISABLED)

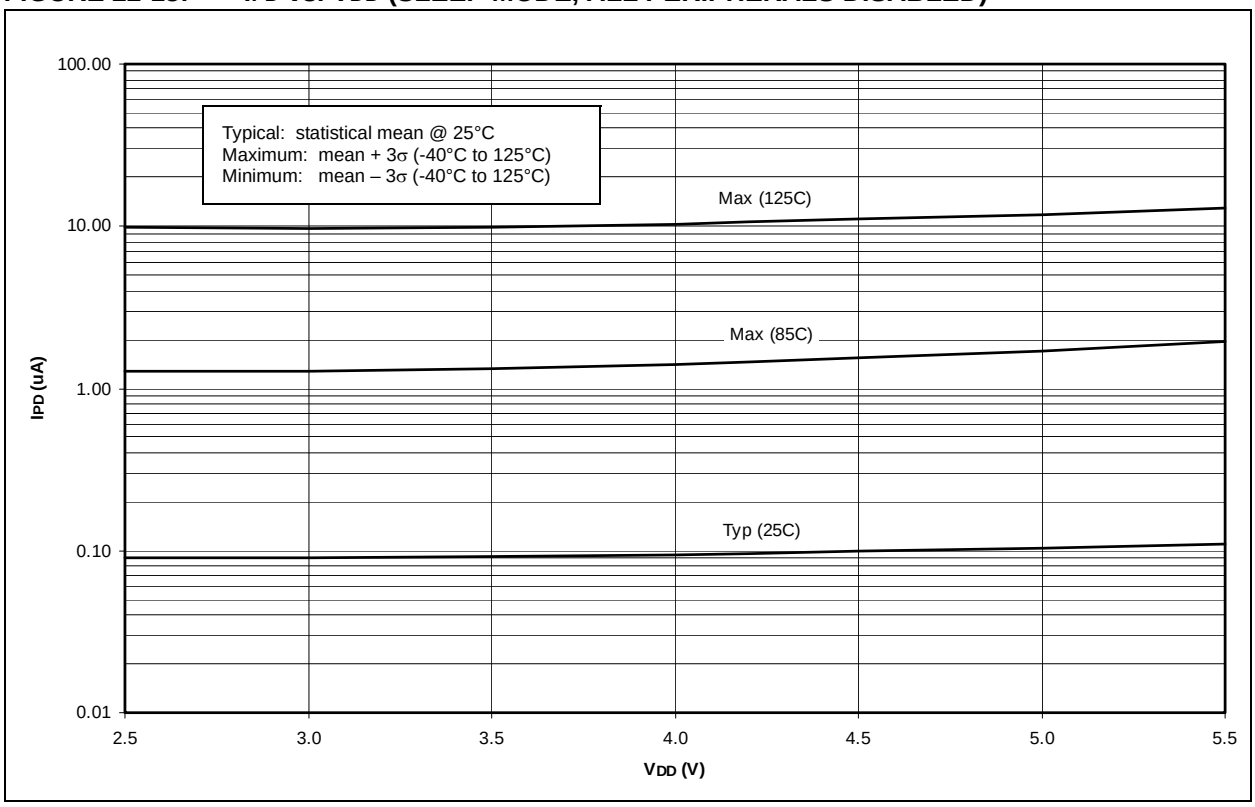


FIGURE 22-14: ΔI_{BOR} VS. V_{DD} OVER TEMPERATURE (BOR ENABLED, V_{BOR} = 2.50V - 2.66V)